



**ALPHA & OMEGA**  
SEMICONDUCTOR

# ***AOS Semiconductor Product Reliability Report***

**AO3418**, rev F

**Plastic Encapsulated Device**

**ALPHA & OMEGA Semiconductor, Inc**

**[www.aosmd.com](http://www.aosmd.com)**

This AOS product reliability report summarizes the qualification result for AO3418. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AO3418 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

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### I. Product Description:

The AO3418 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

Details refer to the datasheet.

### II. Die / Package Information:

|                       |   |
|-----------------------|---|
|                       | <b>AO3418</b>                               |
| <b>Process</b>        | Standard sub-micron<br>30V N-Channel MOSFET |
| <b>Package Type</b>   | SOT23                                       |
| <b>Lead Frame</b>     | Bare Cu                                     |
| <b>Die Attach</b>     | Ag Epoxy                                    |
| <b>Bond</b>           | Au & Cu Wire                                |
| <b>Mold Material</b>  | Epoxy resin with silica filler              |
| <b>Moisture Level</b> | Level 1                                     |

### III. Reliability Stress Test Summary and Results

| Test Item         | Test Condition   | Time Point                | Total Sample Size | Number of Failures | Reference Standard |
|-------------------|--|---------------------------|-------------------|--------------------|--------------------|
| HTGB              | Temp = 150°C ,<br>Vgs=100% of Vgsmax                     | 168 / 500 /<br>1000 hours | 924 pcs           | 0                  | JESD22-A108        |
| HTRB              | Temp = 150°C ,<br>Vds=80% of Vdsmax                      | 168 / 500 /<br>1000 hours | 924 pcs           | 0                  | JESD22-A108        |
| MSL Precondition  | 168hr 85°C / 85%RH +<br>3 cycle reflow @260°C<br>(MSL 1) | -                         | 6699 pcs          | 0                  | JESD22-A113        |
| HAST              | 130°C , 85%RH,<br>33.3 psia,<br>Vds = 80% of Vdsmax      | 96 hours                  | 924 pcs           | 0                  | JESD22-A110        |
| H3TRB             | 85°C , 85%RH,<br>Vds = 80% of Vdsmax                     | 1000 hours                | 693 pcs           | 0                  | JESD22-A101        |
| Autoclave         | 121°C , 29.7psia,<br>RH=100%                             | 96 hours                  | 1848 pcs          | 0                  | JESD22-A102        |
| Temperature Cycle | -65°C to 150°C ,<br>air to air,                          | 250 / 500<br>cycles       | 1848 pcs          | 0                  | JESD22-A104        |
| HTSL              | Temp = 150°C   | 1000 hrs                  | 924 pcs           | 0                  | JESD22-A103        |
| Power Cycling     | Δ Tj = 100°C   | 15000<br>cycles           | 462 pcs           | 0                  | AEC Q101           |

Note: The reliability data presents total of available generic data up to the published date.

### IV. Reliability Evaluation

**FIT rate (per billion): 2.54**

**MTTF = 44879 years**

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

$$\text{Failure Rate} = \text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)] = 2.54$$

$$\text{MTTF} = 10^9 / \text{FIT} = 44879 \text{ years}$$

**Chi<sup>2</sup>** = Chi Squared Distribution, determined by the number of failures and confidence interval

**N** = Total Number of units from burn-in tests

**H** = Duration of burn-in testing

**Af** = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [**Af**] =  $\text{Exp} [Ea / k (1/Tj u - 1/Tj s)]$

**Acceleration Factor ratio list:**

|           | 55 deg C   | 70 deg C  | 85 deg C  | 100 deg C | 115 deg C   | 130 deg C   | 150 deg C |
|-----------|------------|-----------|-----------|-----------|-------------|-------------|-----------|
| <b>Af</b> | <b>259</b> | <b>87</b> | <b>32</b> | <b>13</b> | <b>5.64</b> | <b>2.59</b> | <b>1</b>  |

**Tj s** = Stressed junction temperature in degree (Kelvin), K = C+273.16

**Tj u** = The use junction temperature in degree (Kelvin), K = C+273.16

**k** = Boltzmann's constant, 8.617164 X 10<sup>-5</sup>eV / K